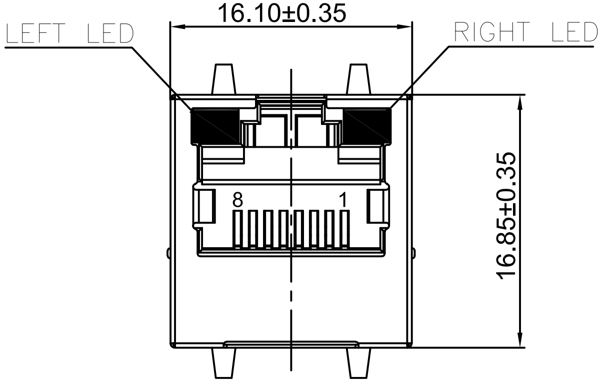
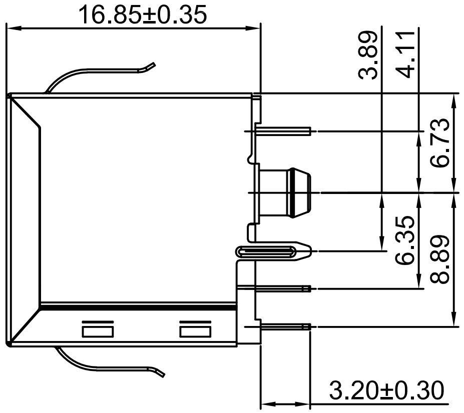
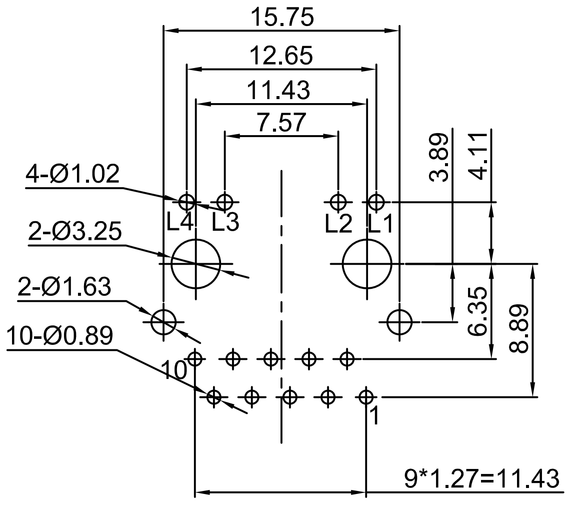
GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2022/10/11	Vince
A0.1			Modify Part No	2023/10/11	Vince
A0.2			Modify Gold plated	2024/01/11	Vince

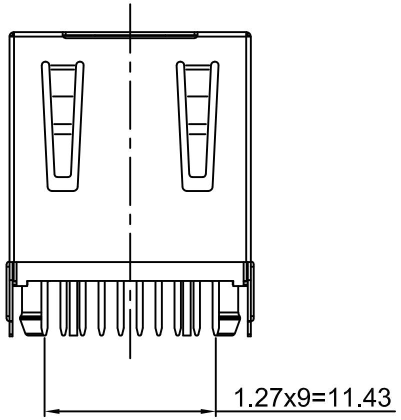
1. MECHANICAL DIMENSIONS :







Suggested PCB Layout(Top View)
(Tolerance:±0.05)



1.Material:
1.1 Housing: PBT UL94V-0 Black.
1.2 Insert core:PBT UL94V-0 Black.
A0.2 1.3 Contact :Phosphor Bronze,Gold plated on contact area 30u",Tin plated on solder area 80u" min, overall nickel plating 30u" min.
1.4 Input Terminal : Brass,Tin plated on solder area 80u" min, Ni underplated overall 30u" min.
1.5 Metal shielding:Copper alloy with Nickel plated.
2.Environmental requirements:
2.1 Lead-free process,compliant RoHS.

MATRIX PART NO:

M R J G - 1 1 T 1705 R S

Matrix-RJ45

F：10/100
G：10/100/1000
N：Pure Connector

11:1X1 ; 21:2X1
12:1X2 ; 22:2X2
14:1X4 ; 24:2X4
16:1X6 ; 26:2X6
18:1X8 ; 28:2X8
1U:RJ+USB

S: SMD
T: THT

Series Number

RS: ROHS
HF: Halogen Free

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TOLERANCE: X. X.X ±0.38 X.XX ±0.25 X.XXX ±0.13 ANGLE: ±3°	DESIGN BY : Vince Chen	DATE : 2024/01/11	PART NAME: RJ45,CONNECTORS,W/LED DIP VERTICAL 8C,10P GIGA,FILTER		
	CHECKED BY: Hanson Huang	DATE : 2024/01/11	PART NO.	MRJG-11T1705RS	
UNIT: mm [inch]	APPROVED BY1: Richard Hsieh	DATE : 2024/01/11	MOLD NO.	NA	
SCALE:1:1	SIZE:A4	APPROVED BY2: Richard Hsieh	DATE : 2024/01/11	DRAW NO. SHEET NO.	1 OF 3

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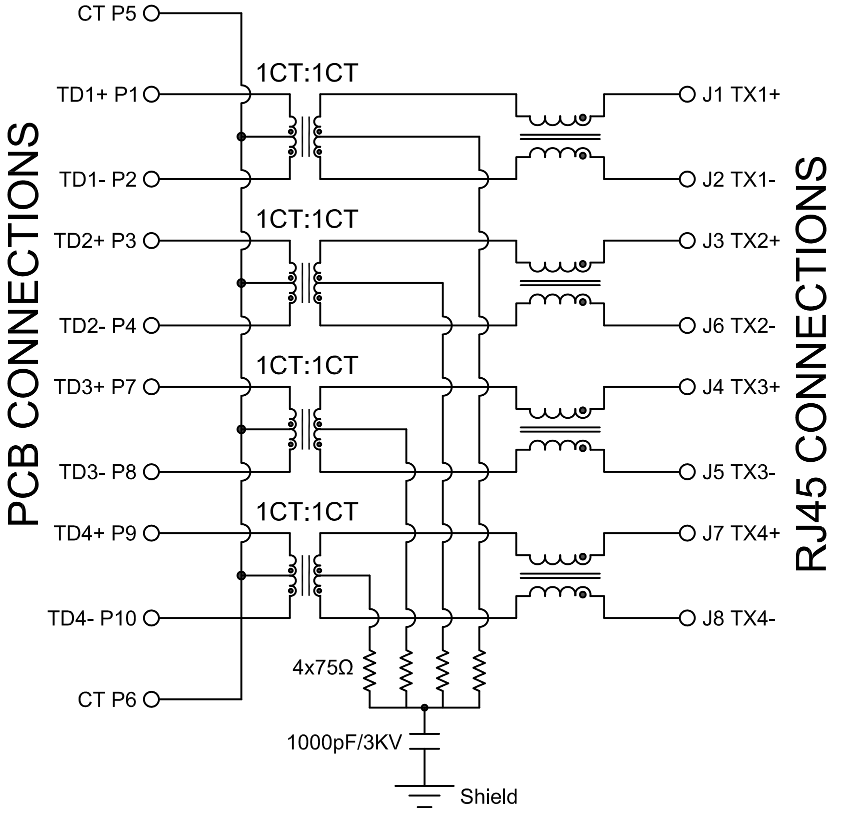
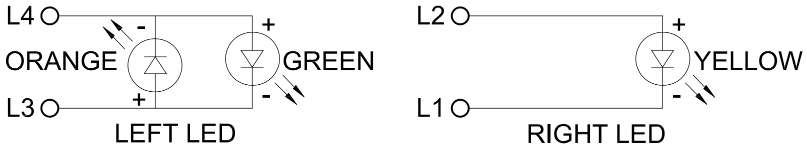
2. SCHEMATIC:





Emitting Color	λ p(nm)	Vf@If=20mA
GREEN	565	1.8-2.5V
YELLOW	585	1.8-2.5V
ORANGE	610	1.8-2.5V

3.Electrical Specification @25°C:

3.1 Inductance: 350uH Min With 8mA DC bias.

3.2 Hi-Pot Test: Input to Output 2250VDC/1mA.

3.3 Insertion loss : 1-100MHZ -1dB max.

3.4 Return loss : 1-30MHZ -18dB min.
30-60MHZ -16dB min.
60-80MHZ -12dB min.
80-100MHZ -10dB min.

3.5 Common Mode Rejection:1-100MHZ -30dB min.

3.6 Cross Talk:1-100MHZ -30dB min.

4.Operating and Storage Temperature:

4.1 Operating Temperature : 0°C to +70°C.

4.2 Storage Temperature : -40°C to +85°C.

5.Wave soldering peak temperature:260°C.

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SCALE:1:1 SIZE:A4			SHEET NO.	2 OF 3

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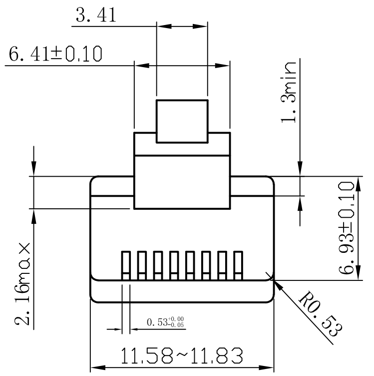
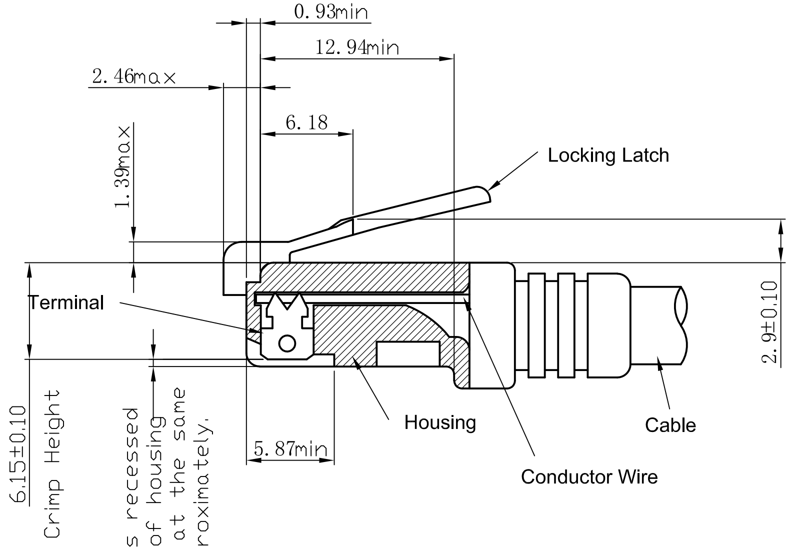


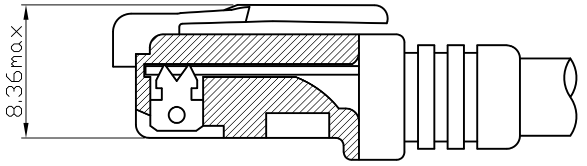
※ There must be no damage to housing or locking latch.There must be no nicks or cuts in cable.
※ Durability : 750 cycles generally



All contacts recessed below top of housing and must be at the same height approximately.

FOLLOW SPECIFICATION : FCC, PART 68, SUBPART F FIGURE 68.500 (C)(2)(i) AND IEC 603-7 FIGURE 23 & 24

STANDARD MODULAR PLUG ASSEMBLY



FOLLOW SPECIFICATION : FCC, PART 68, SUBPART F FIGURE 68.500 (C)(2)(ii)

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UNIT: mm [inch]	**APPROVED BY1:** Richard Hsieh	**DATE :** 2024/01/11	**MOLD NO.**	NA
SCALE:1:1 **SIZE:A4**	**APPROVED BY2:** Richard Hsieh	**DATE :** 2024/01/11	**DRAW NO.** **SHEET NO.**	 3 OF 3